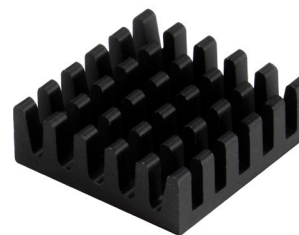




MODEL: HSB04-171706 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- small footprint
- aluminum alloy
- black anodized finish



MODEL

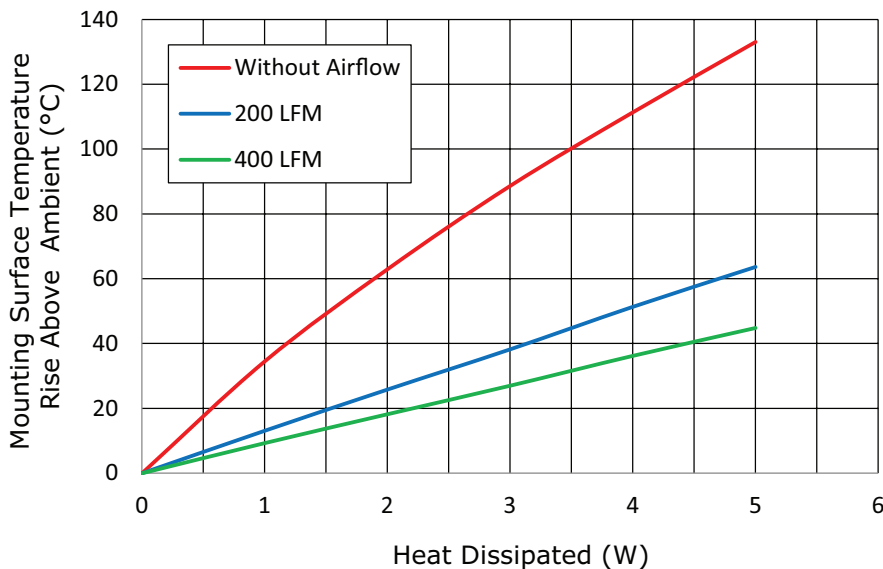
	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB04-171706	29.73	34.5	13.1	9.3	2.52

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	34.5	13.1	9.3
2	62.9	25.8	18.2
3	88.6	38.2	27.0
4	111.3	51.3	36.2
5	133.0	63.6	44.8

T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



CUI DEVICES | **MODEL:** HSB04-171706 | **DESCRIPTION:** HEAT SINK

MECHANICAL DRAWING

units: mm
tolerance: ± 0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	2.7 g

